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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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Keep safety first in your circuit designs!

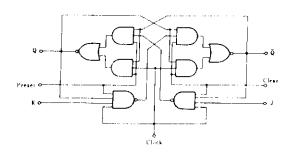
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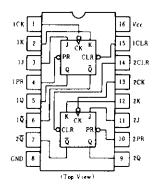
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## **■BLOCK DIAGRAM**(½)

## **■PIN ARRANGEMENT**





## **■RECOMMENDED OPERATING CONDITIONS**

Ite	Symbol	min	typ	max	Unit	
Clock frequency	felock	0	_	30	MHz	
Pulse width	Clock High	tu	20	_		ns
	Clear Preset Low		25	_		
	"H"Data		20 t	-		
Setup time	"L"Data	tru .	20↓	-		ns
Hold time		th	01	_		ns

Note) 1; The arrow indicates the falling edge.

## **EFUNCTION TABLE**

	Outputs					
Preset	Clear	Clock	J	K	Q	Q
L	Н	×	×	×	Н	L
Н	L	×	×	×	L	Н
L	L	×	×	×	Н•	н.
Н	Н	Ţ	L	L	Qo	Qσ
Н	Н	Ī	Н	L	Н	L
Н	Н	ļ	L	Н	L	Н
Н	Н	ļ	Н	Н	Toggle	
Н	Н	н	×	×	Qo	$\overline{\mathbf{Q}}_{0}$

Notes) H; high level, L; low level, X; irrelevant

1; transition from high to low level

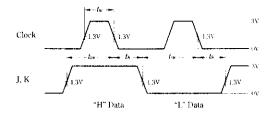
 $Q_0$ ; level of Q before the indicated steady-state input conditions were established.

 $\overline{Q}_0$ ; complement of  $Q_0$  or level of  $\overline{Q}$  before the indicated steady-state input conditions were established.

Toggle; each output changes to the complement of its previous level on each active transition indicated by 1.

\*: This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (high) level.

## **ETIMING DEFINITION**



## **ELECTRICAL CHARACTERISTICS** ( $Ta = -20 \sim +75$ °C)

Item		Symbol	Test Conditions		min	typ*	max	Unit
Input voltage		ViH			2.0		-	V
		VIL					0.8	v
		Von	$V_{CC} = 4.75 \text{V}, V_{IH} = 2 \text{V}, V_{IL} = 0.8 \text{V}, I_{OH} = -400 \mu\text{A}$		2.7	_		v
Output voltage			$V_{CC}=4.75V$ , $V_{IH}=2V$	IoL = 8mA	_		0.5	V
		Vol	$V_{IL}=0.8V$	IoL = 4mA		-	0.4	
	J. K				-	_	20	
	Clear		$V_{CC} = 5.25 \text{V},  V_I = 2.7 \text{V}$		_		60	μΑ
	Preset	ItH			_		60	
	Clock	1		_		80		
	J, K				_	_	0.4	A
Input current	Clear					_	-0.8	
	Preset	IIL**	$V_{CC} = 5.25 \text{V},  V_I = 0.4 \text{V}$		-		-0.8	mA.
	Clock	1			_	**	-0.8	ļ
	J, K	<u> </u>	$V_{CC} = 5.25 \text{V},  V_I = 7 \text{V}$		-	-	0.1	mA
	Clear	1 .				- 1	0.3	
	Preset	- It			-		0.3	
	Clock	1			_		0.4	
Short-circuit output current		Ios	Vcc = 5.25V		- 20	_	-100	mA
Supply current * * * Icc Vcc=5.25V			-	4	8	mА		
Input clamp volta		Vik	$V_{CC} = 4.75V$ , $I_{IN} = -18mA$		_		-1.5	٧

VCC = 5V, Ta = 25°C

## **ESWITCHING CHARACTERISTICS** (Vcc = 5V, $Ta = 25^{\circ}C$ )

Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Maximum clock frequency	fmax				30	45		MHz
	tPLH	Clear	0.75	$C_L = 15 \text{pF}, R_L = 2 \text{k}\Omega$	_	11	20	ns
Propagation delay time	tphl	Preset Clock	Q, Q			15	30	ns

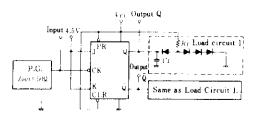
IIL should not be measured when preset and clear inputs are low at same time. With all outputs open, ICC is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

## HD74LS112

### **TESTING METHOD**

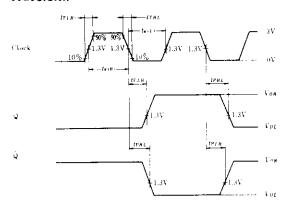
## 1) Test Circuit

1.1)  $f_{max}$ ,  $t_{PLH}$ ,  $t_{PHL}$  (Clock  $\rightarrow \mathbf{Q}, \overline{\mathbf{Q}}$ )



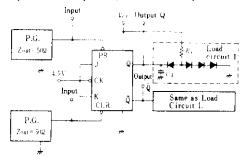
- Notes) 1. Test is put into the each flip-flop.
  - 2. All diodes are 1\$2074 (B).
  - 3. C<sub>L</sub> includes probe and jig capacitance.

#### Waveform

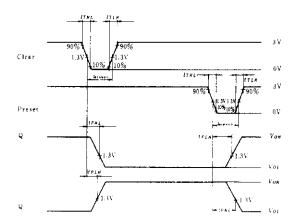


Note) Clock input pulse;  $t_{TLH} \le 15$ ns,  $t_{THL} \le 6$ ns, PRR = 1MHz, duty cycle=50% and: for  $f_{mdx}$ ,  $t_{TLH} = t_{THL} \le 2.5$ ns.

#### 1.2) tPHL, tPLH (Clear, Preset → Q,Q)



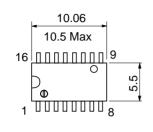
- Notes) 1. Test is put into the each flip-flop.
  - 2. All diodes are 1S2074 (H).
  - 3.  $C_L$  includes probe and jig capacitance.

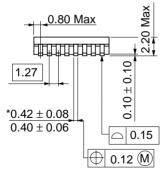


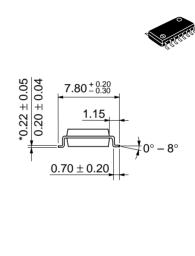
Note) Clear and preset input pulse;  $t_{TLH} \le 15$ ns,  $t_{THL} \le 6$ ns, PRR=1MHz

Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min  $0.25^{+0.13}_{-0.05}$  $0.48 \pm 0.10$  $2.54\pm0.25$  $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm







\*Dimension including the plating thickness
Base material dimension

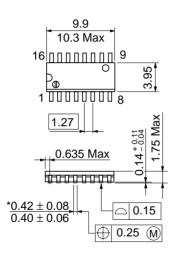
EIAJ Conforms
Weight (reference value) 0.24 g

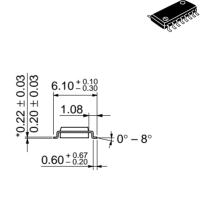
FP-16DA

Hitachi Code

**JEDEC** 

Unit: mm





\*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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